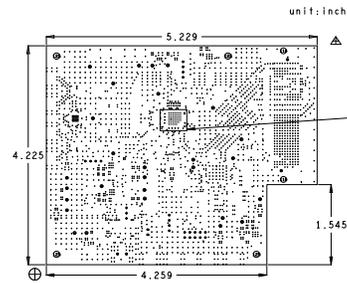


FAB NOTES:

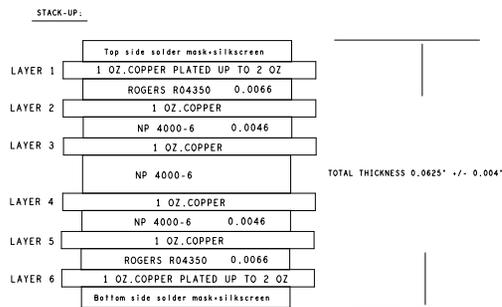
NOTES:

1. USE TARGETS   FOR FILM AND SILKSCREEN REGISTRATION
2. FABRICATE PER CURRENT IPC-6012A SPECIFICATION, CLASS II STANDARD.
3. MATERIAL: ROGERS R04350 + NELCO 4000-6 .SEE STACKUP DRAWING FOR DETAILS.
4. FINISH: HARD GOLD 35 TO 50 MICRO INCHES OVER 150 TO 200 MICRO INCHES NICKEL.
5. APPLY LPI SOLDERMASK ON FRONT & REAR. COLOR:RED
USE APPLICABLE SOLDERMASK FOR FRONT & REAR AS INDICATED.
SOLDERMASK SPREAD IS: .003 PER SIDE.
6. SILKSCREEN USING WHITE EPOXY INK. (USE APPLICABLE SILKSCREEN FOR FRONT & REAR AS INDICATED).
7. MAINTAIN TIGHT TRACE CONTROL TOWARDS CENTER OF BOARD. BOARD HOUSE CAN MODIFY TRACE OR DIELECTRIC CALLOUT IN STACK-UP TO ACHIEVE 100 OHM +/- 10% DIFFERENTIAL 0.008" TRACES WITH 0.008" SPACE AND 50 OHM +/- 10% SINGLE ENDED WITH 0.013".
8. ALL DIELECTRIC CALLOUTS NEED TO BE MICROMETER MEASURED AND CONSISTENT FOR ALL PANELS.
9. USE FOIL LAMINATION OR CAP LAMINATION WHICH EVER IS MORE COST EFFECTIVE. COPPER THICKNESS: 2 OZ TOP & BOTTOM LAYERS, 1 OZ ALL INNER LAYERS.
10. BOARD OVERALL THICKNESS WITH INDICATED TOLERANCE IS TO BE MEASURED FROM THE HIGHEST POINT (METAL CLAD / PLATING AND SOLDERMASK INCLUDED, EXCLUDING SILKSCREEN) OF THE TOP AND BOTTOM OF BOARD.
11. WARPAGE NOT TO EXCEED 0.5%, BOW OR TWIST.
12. PCB MUST MEET ROHS COMPLIANCE.
13. HOLES 12F OR ENTIRE AREA MUST BE FILLED WITH CONDUCTIVE MATERIAL CB100 OR EQUIV WHICH EVER IS MORE COST EFFECTIVE. MATERIAL CHOICE IS A BOARD VENDOR OPTION. HOLE FLATNESS TO BE +.000/- .001 ON BOTTOM SIDE. HOLE FLATNESS TO BE +.000/- .003 ON TOP SIDE.



TEXAS INSTRUMENTS
FAB NOTES
DESIGNER
DATE
FAB_DWG
ADC16DX370EVM_R2.brd
DATE: 10/15/2013
BY:

DRILL CHART: TOP TO BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
-	8.0	PLATED	46
13	12.0	PLATED	2449
-	12.0	PLATED	17
+	36.0	PLATED	2
+	37.0	PLATED	22
+	38.0	PLATED	3
*	56.0	PLATED	4
*	63.0	PLATED	23
⊙	116.0	PLATED	2
⊙	125.0	PLATED	4
+	46.0	NON-PLATED	2
+	51.0	NON-PLATED	2
*	59.84	NON-PLATED	1



BOARD NAME

ADC16DX370EVM REV: 2.0